Impedance Control:

- Top layer contains 50 ohm impedance (±10%) single ended using 24 mil lines (from E1 to U8)
Impedance Control:
- Top layer contains 50 ohm impedance (±10%) single ended using 24mil lines (from E1 to U9)
Impedance Control:

- Top layer contains 95 ohm impedance (+/- 10%) single ended using 24 multilines (from E1 to U8)

**Layer Name** | **Material** | **Thickness Constant** | **Board Layer Stack**
--- | --- | --- | ---
Top Overlay | | |  
Top Solder | | |  
Top Layer | | |  
Dielectric | | |  
Signal Layer 1 | | |  
Signal Layer 2 | | |  
Bottom Layer | | |  
Bottom Solder | | |  
Bottom Overlay | | |  

**Material**
- FR-4
- FR-4 High Tg
- Other

**Thickness**
- 62 μm (0.60mm) +/- 10% on other side
- 3 μm

**Tolerance**
- ANSI IPC-6012 TYPE 5 CLASS 2
- Other +/-

**Board Finish**
- Solder
- Copper

**Surface Finish**
- Immersion Gold (Ig)
- Immersion Hard Gold

**Chip Placement**
- Cut and Trim Per Grid Criteria
- Off-Center

**Certification**
- UL 94V-0 and RoHS Compliant

**PBGA Pad Size**
- 3.0 x 3.0 mm

**Dimensions**
- 110.0 x 110.0 mm
- 100.0 x 100.0 mm

**Comments**
- DOI: 10.3181/1.190371
- Texas Instruments

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**NOTE:**

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**DESIGN INFORMATION**
- **Track Width:** 1.046 mm
- **Track Spacing:** 0.318 mm
- **Board Size:** 110.0 x 110.0 mm
- **Assembly Method:** SMT
- **Number of Layers:** 1
- **Compliance:** RoHS
- **Certification:** UL 94V-0
- **Model:** TBD-00756

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**Design:**
- **Name:** Gustavo Hernandez
- **Company:** Krypton Solutions-RS
- **Date:** 16.09.368

** Freelance:** 1.00

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**Low Power CO2 Gas Sensor w/ BLE Connectivity**
- **Application:** Public Release
- **Board:** TBD-00756
- **Document:** PcbDoc

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**PROJECTS:**
- **Name:** Low Power CO2 Gas Sensor w/ BLE Connectivity
- **Status:** Public Release
- **Document:** TBD-00756

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**COMPONENTS:**
- **Legend:**
  - **SMD:** Surface Mount Device
  - **THT:** Through-Hole Technology
  - **CO:** Capacitor
  - **RI:** Resistor
  - **BU:** Button
  - **TS:** Terminal Strip
  - **PD:** Power Down

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**REFERENCES:**
- **Title:** SMD Components Reference
- **Author:** Texas Instruments
- **Edition:** 4.0

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**NOTES:**
- **SMD Component Values:**
  - **Capacitor Values:** 100uF, 0.1uF
  - **Resistor Values:** 10kΩ, 1kΩ
  - **Inductor Values:** 10μH, 47μH

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**Legend:**
- **Colors:** Green, Red, Blue, White, Black
- **Marking:** SMD, THT
- **Symbols:** C, R, L

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**Assembly:**
- **Method:** SMT
- **Components:**
  - **Capacitors:** 100uF, 0.1uF
  - **Resistors:** 10kΩ, 1kΩ
  - **Inductors:** 10μH, 47μH

---

**Board Layout:**
- **Dimensions:** 110.0 x 110.0 mm
- **Layers:** 1
- **Orientation:** Top View

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**Notes:**
- **Compliance:** RoHS
- **Certification:** UL 94V-0
- **Model:** TBD-00756
- **Document:** PcbDoc

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**Design:**
- **Name:** Gustavo Hernandez
- **Company:** Krypton Solutions-RS
- **Date:** 16.09.368
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